

## General Description

The 50N06B combines advanced trench MOSFET technology with a low resistance package to provide extremely low RDS(ON).

This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

## Features

- Low On-Resistance
- 100% Avalanche Tested
- RoHS Compliant

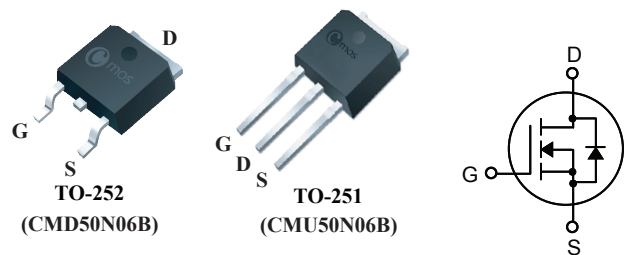
## Product Summary

BVDSS	RDS(on)	ID
60V	13mΩ	50A

## Applications

- DC-DC & DC-AC Converters
- Motor Control, Audio Amplifiers
- High Current, High Speed Switching
- Primary Switch for 12V and 24V system

## TO-252/251 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current <sup>1</sup>	50	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current <sup>1</sup>	35	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	150	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	85	mJ
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	75	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	50	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction -Case	---	2.1	$^\circ\text{C/W}$

## Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=250\mu A$	60	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V$ , $I_D=50A$	---	10	13	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	2	---	4	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=60V$ , $V_{GS}=0V$ , $T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=60V$ , $V_{GS}=0V$ , $T_J=125^{\circ}\text{C}$	---	---	100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=10V$ , $I_D=20A$	---	15	---	S
$R_g$	Gate Resistance	$V_{DS}=0V$ , $V_{GS}=0V$ , $f=1\text{MHz}$	---	1.2	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{DS}=30V$ , $V_{GS}=10V$ , $I_D=50A$	---	35	---	nC
$Q_{gs}$	Gate-Source Charge		---	10	---	
$Q_{gd}$	Gate-Drain Charge		---	8	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V$ , $V_G=10V$ , $R_G=9.6\Omega$ $I_D=50A$	---	12	---	ns
$T_r$	Rise Time		---	86	---	
$T_{d(off)}$	Turn-Off Delay Time		---	35	---	
$T_f$	Fall Time		---	26	---	
$C_{iss}$	Input Capacitance	$V_{DS}=30V$ , $V_{GS}=0V$ , $f=1\text{MHz}$	---	2200	---	pF
$C_{oss}$	Output Capacitance		---	210	---	
$C_{rss}$	Reverse Transfer Capacitance		---	110	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1</sup>	$V_G=V_D=0V$ , Force Current	---	---	50	A
$I_{SM}$	Pulsed Source Current <sup>2</sup>		---	---	150	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V$ , $I_S=20A$ , $T_J=25^{\circ}\text{C}$	---	---	1.25	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V$  ,  $V_{GS}=10V$  ,  $L=0.1\text{mH}$  ,  $I_{AS}=36A$ .

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